



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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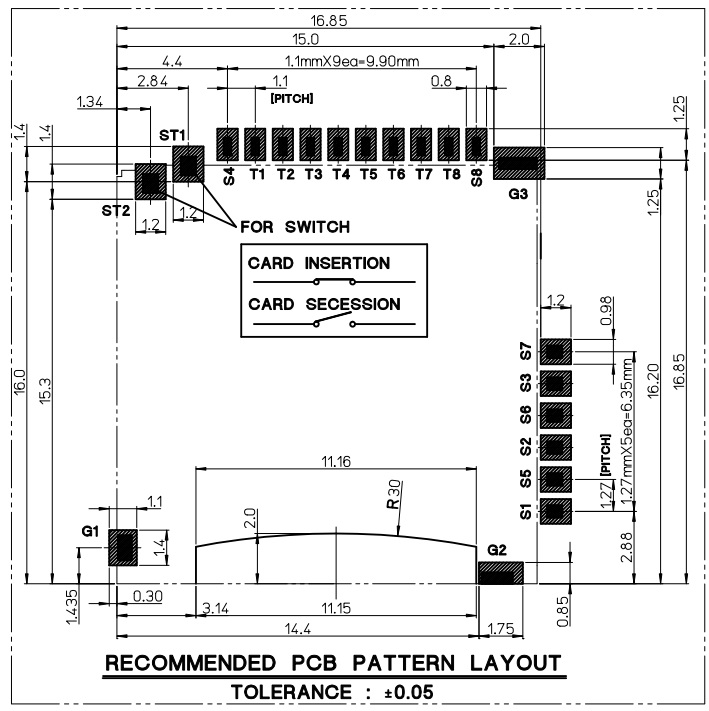
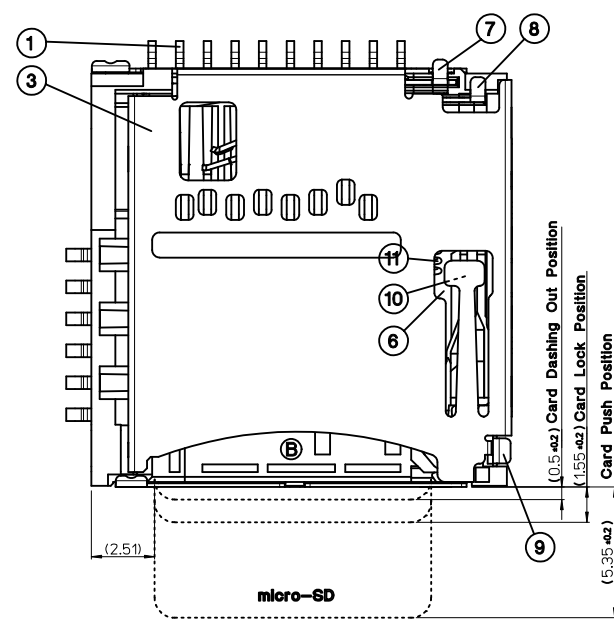
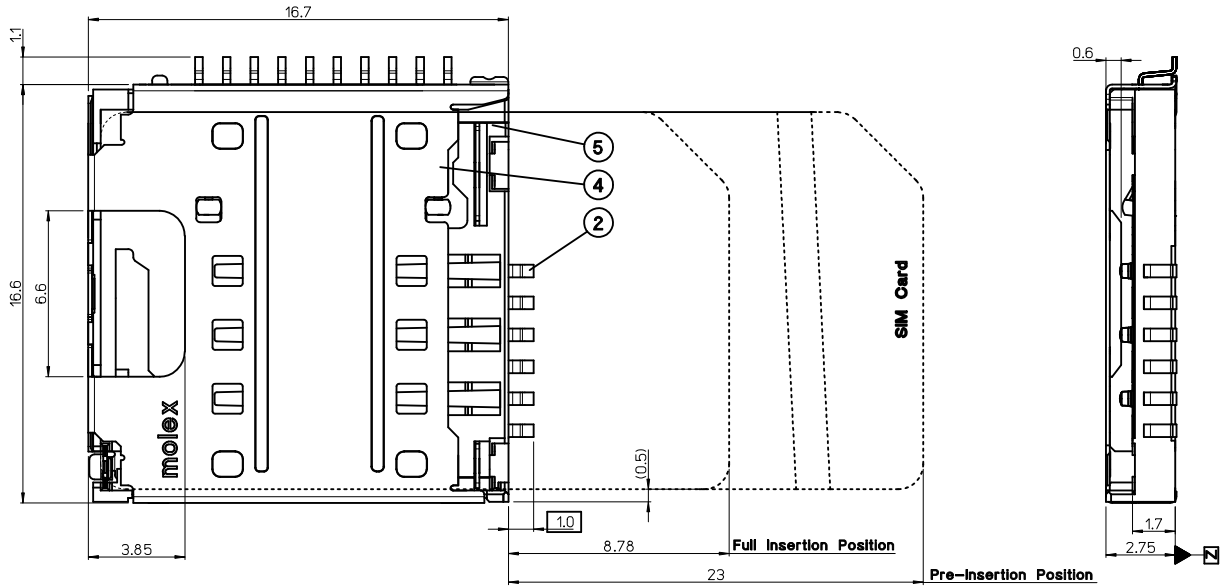
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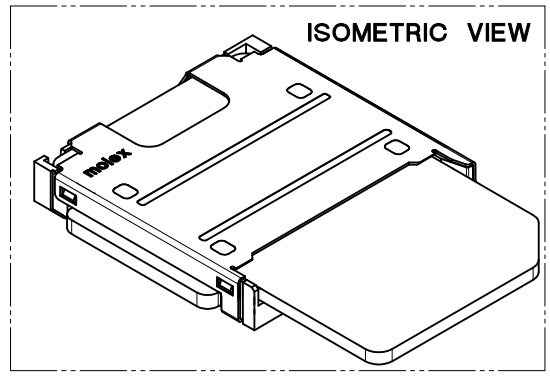


10 9 8 7 6 5 4 3 2 1



NOTES

1. MATERIALS: SEE TABLE 2
2. FINISHES: SEE TABLE 2
3. PRODUCT SPECIFICATION : PS-49448-001
4. COPLANARITY OF SOLDER TAILS : 0.1mm MAX.
MISALIGNMENT OF SOLDER TAIL FROM "Z"
UPPER DIRECTION 0.05 MAX., LOWER DIRECTION 0.1MAX.
5. PACKAGING SPECIFICATION : PK-49448-001



*** TABLE 1**

494481611	49448-1611
MATERIAL NO.	ORDER NO.

REVISED EC NO: KOR2012-0006 DRWN:HYOU 2011/07/14 CHKD: APPR: YUNSIKKIM 2011/07/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla = 0$ $\nabla C = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.1 ± --- 1 PLACE ± 0.15 ± --- ANGULAR ± 1 °	MM ONLY	5:1	METRIC	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE S. H. CHU 2008/10/20 CHECKED BY DATE S. J. SEH 2008/10/20 APPROVED BY DATE E. H. JUNG 2008/10/20 MATERIAL NO.	TITLE M-SD/SIM COMBO SOCKET FOR 8P/8P (BERYLLIUM FREE)			
	SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-49448-001 SHEET NO. 1 OF 3				

9 8 7 6 5 4 3 2 1

* TABLE 1 : PARTS-LIST

NO.	DESCRIPTION	ENGINEERING NO.	MATERIALS	FINISHES
1	mSD-CONTACT TERMINAL	49932-8031	PHOS.-BRONZE	Selective-Au over Ni
2	S-CONTACT TERMINAL	49814-8031	COPPER-ALLOY (C)	Selective-Au over Ni
3	mSD-METAL SHELL	49933-5003	STAINLESS STEEL	Ni OVERALL
4	S-METAL SHELL	49934-5003	STAINLESS STEEL	Ni OVERALL
5	HOUSING	49448-1691	LIQUID CRYSTAL POLYMER	UL94V-0
6	HEART CAM	49363-0001	LIQUID CRYSTAL POLYMER	UL94V-0
7	SWITCH TERMINAL 1	49820-8031	PHOS.-BRONZE	Selective-Au over Ni
8	SWITCH TERMINAL 2	49821-8031	PHOS.-BRONZE	Selective-Au over Ni
9	FITTING NAIL	49819-8003	PHOS.-BRONZE	PURE-Sn over Ni
10	PIN ROD	49225-9002	STAINLESS STEEL	
11	SPRING	49362-9001	STAINLESS STEEL	

* TABLE 2 : REFERENCE

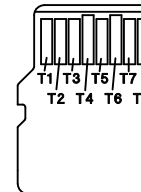
[SIM CARD-8P PIN-MAP]

PIN NUMBER	DESCRIPTION
S1	Vcc(Voltage)
S2	Vcc(Reset)
S3	CLK
S4	Reserved
S5	GND
S6	Vpp
S7	I/O
S8	Reserved

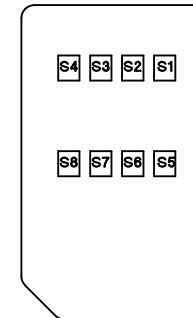
[microSD CARD PIN-MAP]

PIN NUMBER	DESCRIPTION
T1	DAT2
T2	CD/DAT3 ²
T3	CMD
T4	V _{DD}
T5	CLK
T6	V _{SS} ²
T7	DAT0
T8	DAT1

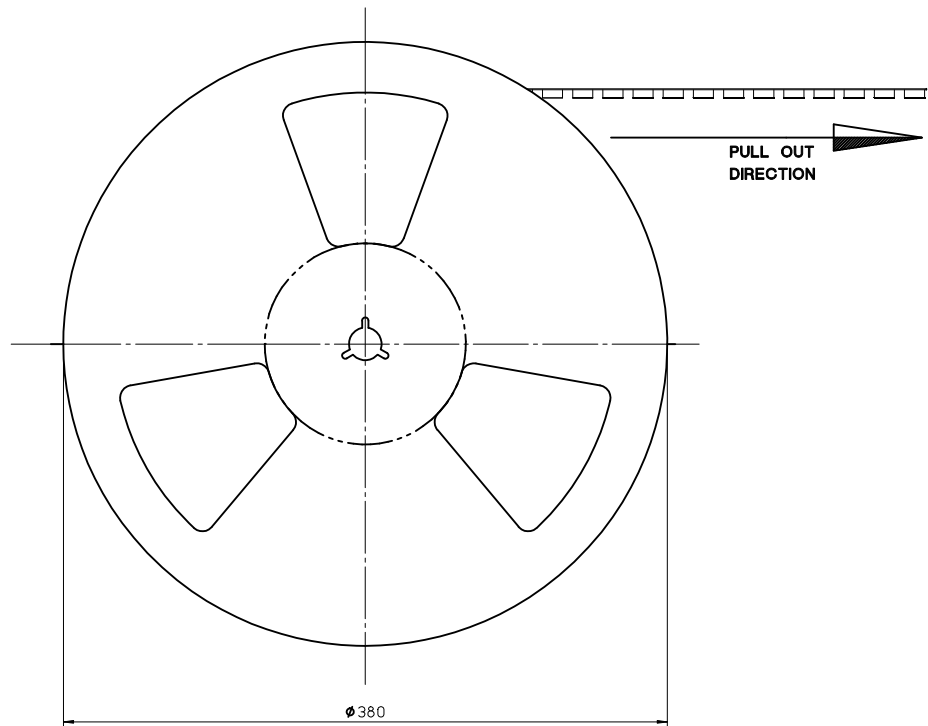
microSD CARD



SIM CARD-8P

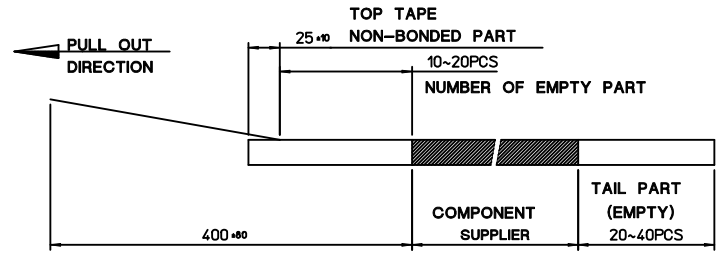


REVISED IEC NO: KOR2012-0006 DRWN: HYU CHKD: APPR: YUNS IKK IM 2011/07/14 2011/07/14 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.1 ± --- 1 PLACE ± 0.15 ± --- ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	5:1	METRIC	
			DRAWN BY DATE	TITLE		
			CHECKED BY DATE	M-SD/SIM COMBO SOCKET FOR 8P/8P (BERYLLIUM FREE)		
	APPROVED BY DATE	MOLEX MOLEX INCORPORATED				
	MATERIAL NO.	DOCUMENT NO.				
	SEE TABLE	SD-49448-001				
	SIZE A3	SHEET NO. 2 OF 3				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

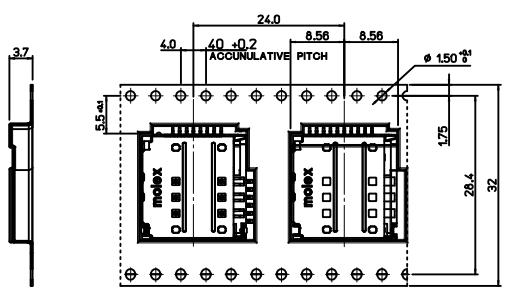
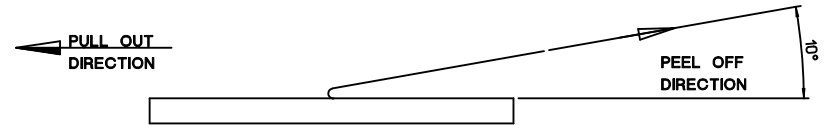


NOTES

- 1. QUANTITY OF CONNECTORS : 1,000PCS/REEL
- 2. LEAD LENGTH



- 3. PEELING OFF FORCE OF COVER TAPE : 0.1N~0.59N(10.2GF~60GF)
(PEELING DIRECTION AS SHOW IN FOLLOW FIG.)
- PEELING OFF SPEED : 300mm/Min.(Ref.)



35902-0011	35908-1003	49362-9901	49448-1611	494481611	49448-1611	8P/8P
COVER TAPE	REEL	EMBOSSED TAPE	CONNECTOR	MATERIAL NO.	ENG. NO.	CKTS

REVISED EC NO: KOR2012-0006 DRWN: IHYOU 2011/07/14 CHKD: APPR: YUNS IKKIM 2011/07/14	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		▼=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.1 ± --- 1 PLACE ± 0.15 ± --- ANGULAR ± 1 °	MM ONLY	5:1	METRIC	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE S. H. CHU 2008/10/20 CHECKED BY DATE S. J. SEH 2008/10/20 APPROVED BY DATE E. H. JUNG 2008/10/20 MATERIAL NO.	TITLE M-SD/SIM COMBO SOCKET FOR 8P/8P (BERYLLIUM FREE) MOLEX INCORPORATED DOCUMENT NO. SD-49448-001	SHEET NO. 3 OF 3	
			SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			